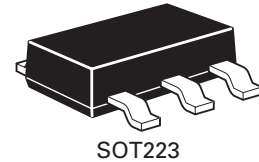


BSP75N

60V self-protected low-side Intellifet™ MOSFET switch

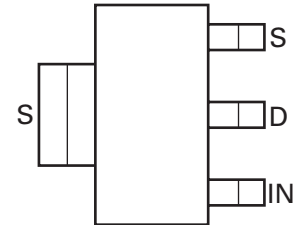
Summary

| | |
|---|------------------------|
| Continuous drain source voltage | $V_{DS}=60V$ |
| On-state resistance | 500mΩ |
| Maximum nominal load current ^(a) | 1.1A ($V_{IN} = 5V$) |
| Minimum nominal load current ^(c) | 0.7A ($V_{IN} = 5V$) |
| Clamping energy | 550mJ |



Description

Self-protected low side MOSFET. Monolithic over temperature, over current, over voltage (active clamp) and ESD protected logic level functionality. Intended as a general purpose switch.



Features

- Short circuit protection with auto restart
- Over-voltage protection (active clamp)
- Thermal shutdown with auto restart
- Over-current protection
- Input protection (ESD)
- High continuous current rating
- Load dump protection (actively protects load)
- Logic level input

Note:

The tab is connected to the source pin and must be electrically isolated from the drain pin. Connection of significant copper to the drain pin is recommended for best thermal performance.

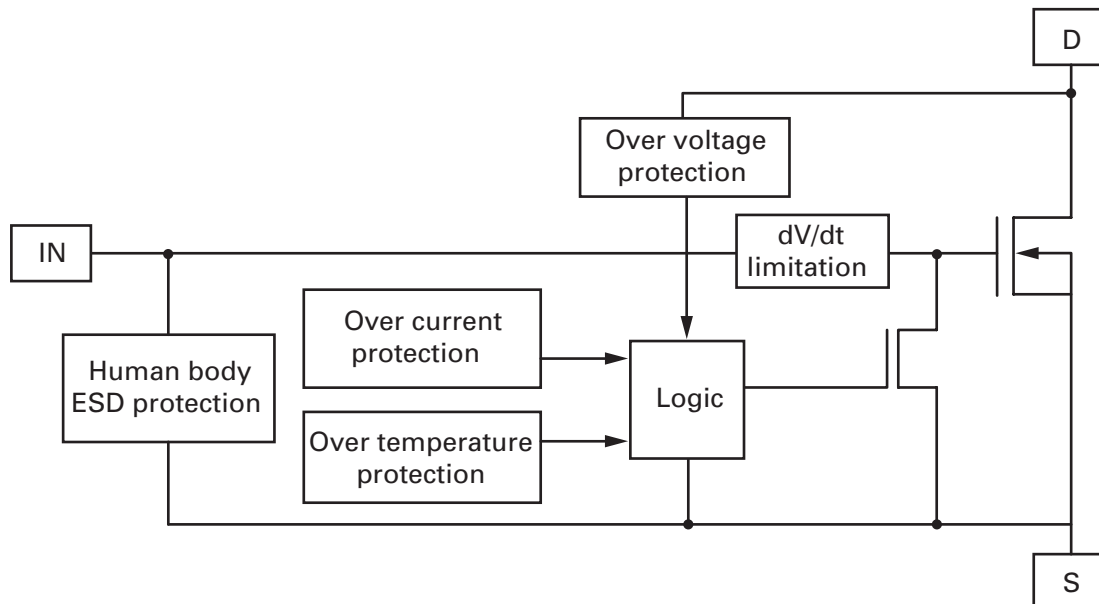
Ordering information

| Device | Reel size (inches) | Tape width (mm) | Quantity per reel |
|----------|--------------------|-----------------|-------------------|
| BSP75NTA | 7 | 12mm embossed | 1000 |

Device marking

BSP75N

Functional block diagram



Applications

- Especially suited for loads with a high in-rush current such as lamps and motors.
- All types of resistive, inductive and capacitive loads in switching applications.
- μC compatible power switch for 12V and 24V DC applications.
- Automotive rated.
- Replaces electromechanical relays and discrete circuits.

Linear mode capability - the current-limiting protection circuitry is designed to de-activate at low V_{ds} , in order not to compromise the load current during normal operation. The design maximum DC operating current is therefore determined by the thermal capability of the package/board combination, rather than by the protection circuitry. This does not compromise the products ability to self protect itself at low V_{DS} .

Absolute maximum ratings

| Parameter | Symbol | Limit | Unit |
|---|----------------|--------------|------|
| Continuous drain-source voltage | V_{DS} | 60 | V |
| Drain-source voltage for short circuit protection $V_{IN} = 5V$ | $V_{DS(SC)}$ | 36 | V |
| Drain-source voltage for short circuit protection $V_{IN} = 10V$ | $V_{DS(SC)}$ | 20 | V |
| Continuous input voltage | V_{IN} | -0.2 ... +10 | V |
| Peak input voltage | V_{IN} | -0.2 ... +20 | V |
| Operating temperature range | T_j | -40 to +150 | °C |
| Storage temperature range | T_{stg} | -55 to +150 | °C |
| Power dissipation at $T_A = 25^\circ C$ ^(a) | P_D | 1.5 | W |
| Power dissipation at $T_A = 25^\circ C$ ^(c) | P_D | 0.6 | W |
| Continuous drain current @ $V_{IN}=10V$; $T_A=25^\circ C$ ^(a) | I_D | 1.3 | A |
| Continuous drain current @ $V_{IN}=5V$; $T_A=25^\circ C$ ^(a) | I_D | 1.1 | A |
| Continuous drain current @ $V_{IN}=5V$; $T_A=25^\circ C$ ^(c) | I_D | 0.7 | A |
| Continuous source current (body diode) ^(a) | I_S | 2.0 | A |
| Pulsed source current (body diode) ^(b) | I_S | 3.3 | A |
| Unclamped single pulse inductive energy | E_{AS} | 550 | mJ |
| Load dump protection | $V_{LoadDump}$ | 80 | V |
| Electrostatic discharge (human body model) | V_{ESD} | 4000 | V |
| DIN humidity category, DIN 40 040 | | E | |
| IEC climatic category, DIN IEC 68-1 | | 40/150/56 | |

Thermal resistance

| Parameter | Symbol | Limit | Unit |
|------------------------------------|-----------------|-------|------|
| Junction to ambient ^(a) | $R_{\theta JA}$ | 83 | °C/W |
| Junction to ambient ^(b) | $R_{\theta JA}$ | 45 | °C/W |
| Junction to ambient ^(c) | $R_{\theta JA}$ | 208 | °C/W |

NOTES:

(a) For a device surface mounted on 25mm x 25mm x 1.6mm FR4 board with a high coverage of single sided 2oz weight copper. Allocation of 6cm² copper 33% to source tab and 66% to drain pin with tab and drain pin electrically isolated.

(b) For a device surface mounted on FR4 board as (a) and measured at $t \leq 10s$.

(c) For a device surface mounted on FR4 board with the minimum copper required for connections.

Electrical characteristics (at $T_{AMB} = 25^{\circ}\text{C}$ unless otherwise stated)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions |
|---|--------------------|------|------|------|------------------------|--|
| Static characteristics | | | | | | |
| Drain-source clamp voltage | $V_{DS(AZ)}$ | 60 | 70 | 75 | V | $I_D=10\text{mA}$ |
| Off-state drain current | I_{DSS} | | 0.1 | 3 | μA | $V_{DS}=12\text{V}, V_{IN}=0\text{V}$ |
| Off-state drain current | I_{DSS} | | 3 | 15 | μA | $V_{DS}=32\text{V}, V_{IN}=0\text{V}$ |
| Input threshold voltage (*) | $V_{IN(th)}$ | 1 | 2.1 | | V | $V_{DS}=V_{GS}, I_D=1\text{mA}$ |
| Input current | I_{IN} | | 0.7 | 1.2 | mA | $V_{IN}=+5\text{V}$ |
| Input current | I_{IN} | | 1.5 | 2.7 | mA | $V_{IN}=+7\text{V}$ |
| Input current | I_{IN} | | 4 | 7 | mA | $V_{IN}=+10\text{V}$ |
| Static drain-source on-state resistance | $R_{DS(on)}$ | | 520 | 675 | $\text{m}\Omega$ | $V_{IN}=+5\text{V}, I_D=0.7\text{A}$ |
| Static drain-source on-state resistance | $R_{DS(on)}$ | | 385 | 550 | $\text{m}\Omega$ | $V_{IN}=+10\text{V}, I_D=0.7\text{A}$ |
| Current limit (†) | $I_{D(LIM)}$ | 0.7 | 1.0 | 1.5 | A | $V_{IN}=+5\text{V}, V_{DS}>5\text{V}$ |
| Current limit (†) | $I_{D(LIM)}$ | 1.0 | 1.8 | 2.3 | A | $V_{IN}=+10\text{V}, V_{DS}>5\text{V}$ |
| Dynamic characteristics | | | | | | |
| Turn-on time (V_{IN} to 90% I_D) | t_{on} | | 3.0 | 10 | μs | $R_L=22\Omega, V_{DD}=12\text{V}, V_{IN}=0$ to $+10\text{V}$ |
| Turn-off time (V_{IN} to 90% I_D) | t_{off} | | 13 | 20 | μs | $R_L=22\Omega, V_{DD}=12\text{V}, V_{IN}=+10\text{V}$ to 0V |
| Slew rate on (70 to 50% V_{DD}) | $-dV_{DS}/dt_{on}$ | | 8 | 20 | $\text{V}/\mu\text{s}$ | $R_L=22\Omega, V_{DD}=12\text{V}, V_{IN}=0$ to $+10\text{V}$ |
| Slew rate off (50 to 70% V_{DD}) | dV_{DS}/dt_{off} | | 3.2 | 10 | $\text{V}/\mu\text{s}$ | $R_L=22\Omega, V_{DD}=12\text{V}, V_{IN}=+10\text{V}$ to 0V |
| Protection functions (‡) | | | | | | |
| Required input voltage for over temperature protection | V_{PROT} | 4.5 | | | V | |
| Thermal overload trip temperature | T_{JT} | 150 | 175 | | $^{\circ}\text{C}$ | |
| Thermal hysteresis | | | 1 | | $^{\circ}\text{C}$ | |
| Unclamped single pulse inductive energy $T_j=25^{\circ}\text{C}$ | E_{AS} | 550 | | | mJ | $I_{D(ISO)}=0.7\text{A}, V_{DD}=32\text{V}$ |
| Unclamped single pulse inductive energy $T_j=150^{\circ}\text{C}$ | | 200 | | | mJ | $I_{D(ISO)}=0.7\text{A}, V_{DD}=32\text{V}$ |
| Inverse diode | | | | | | |
| Source drain voltage | V_{SD} | | | 1 | V | $V_{IN}=0\text{V}, -I_D=1.4\text{A}$ |

NOTES:

(*) The drain current is limited to a reduced value when V_{DS} exceeds a safe level.

(†) Protection features may operate outside spec for $V_{IN}<4.5\text{V}$.

(‡) Integrated protection functions are designed to prevent IC destruction under fault conditions described in the datasheet. Fault conditions are considered as "outside" normal operating range. Protection functions are not designed for continuous, repetitive operation.

Application information

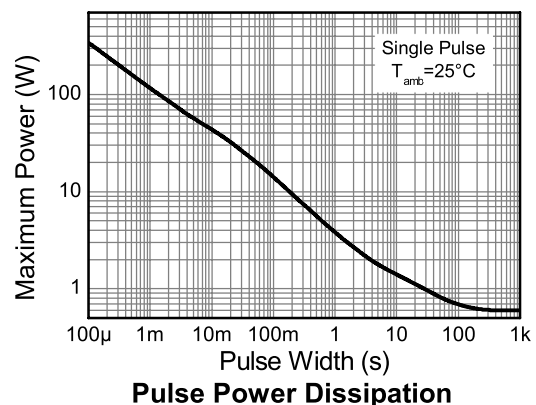
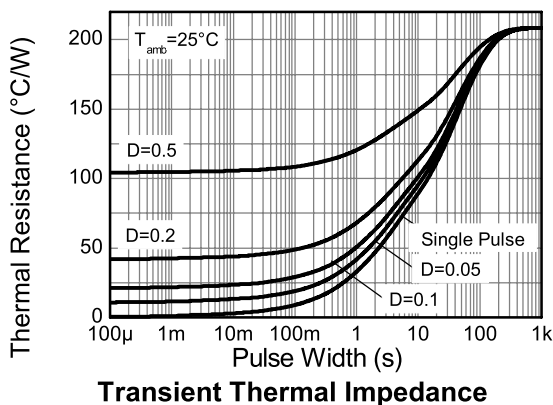
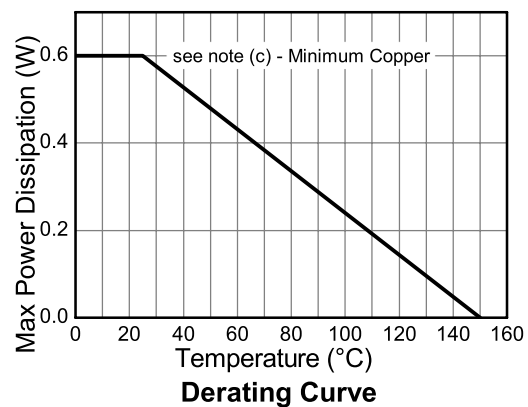
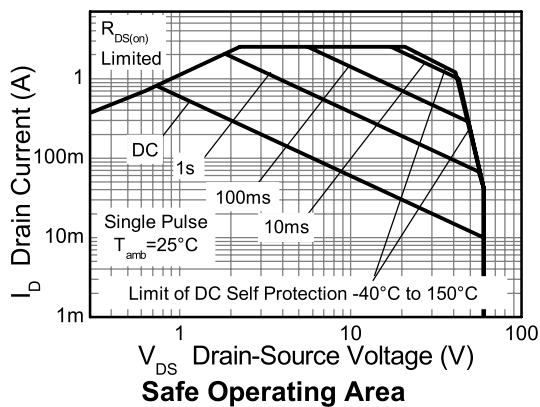
The current-limit protection circuitry is designed to de-activate at low V_{DS} to prevent the load current from being unnecessarily restricted during normal operation. The design max DC operating current is therefore determined by the thermal capability of the package/board combination, rather than by the protection circuitry (see graph on page 7 'Typical Output Characteristic'). This does not compromise the products ability to self protect at low V_{DS} .

The overtemperature protection circuit trips at a minimum of 150°C. So the available package dissipation reduces as the maximum required ambient temperature increases. This leads to the following maximum recommended continuous operating currents.

Minimum copper area characteristics

For minimum copper condition as described in note (c)

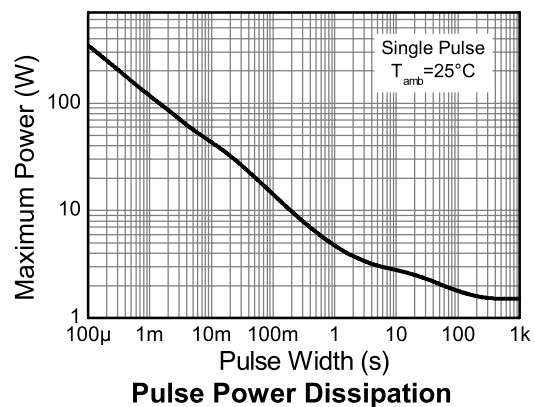
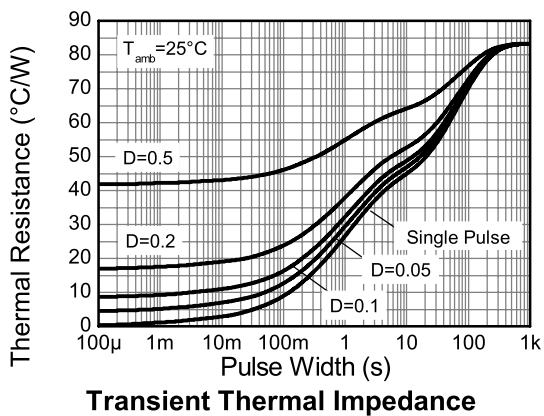
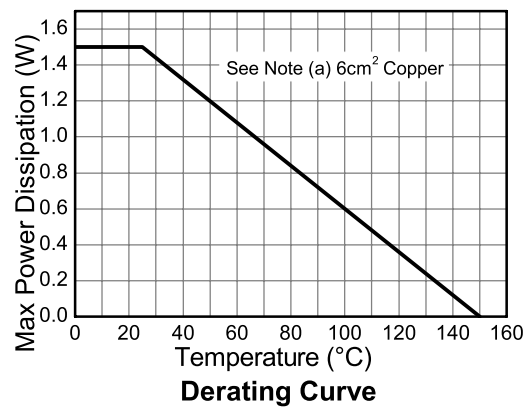
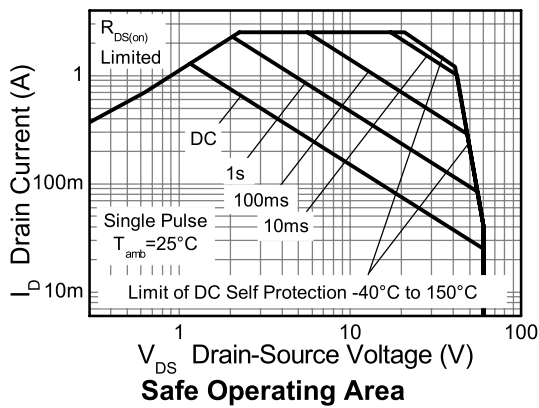
| Max. ambient temperature T_{amb} | Maximum continuous current | |
|------------------------------------|----------------------------|----------------|
| | $V_{IN} = 5V$ | $V_{IN} = 10V$ |
| 25°C @ $V_{IN} = 5V$ | 720 | 840 |
| 70°C @ $V_{IN} = 5V$ | 575 | 670 |
| 85°C @ $V_{IN} = 5V$ | 520 | 605 |
| 125°C @ $V_{IN} = 5V$ | 320 | 375 |



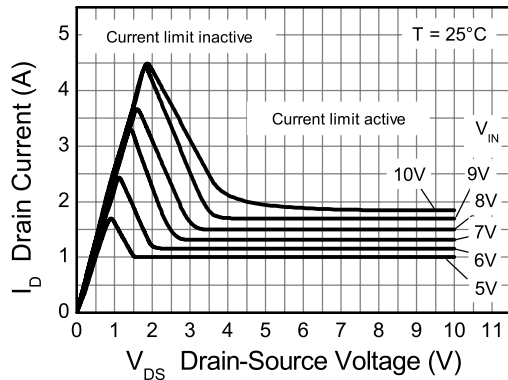
Large copper area characteristics

For large copper area as described in note (a)

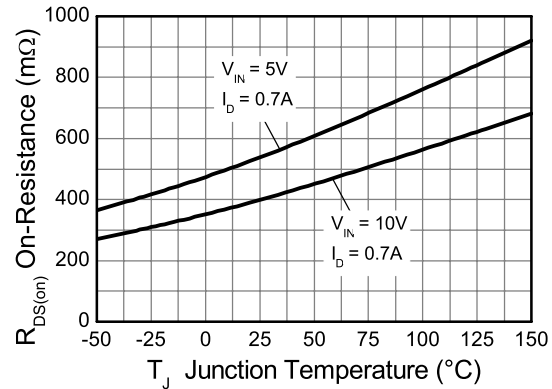
| Max. ambient temperature T_{amb} | Maximum continuous current | |
|------------------------------------|----------------------------|----------------|
| | $V_{IN} = 5V$ | $V_{IN} = 10V$ |
| 25°C @ $V_{IN} = 5V$ | 1140 | 1325 |
| 70°C @ $V_{IN} = 5V$ | 915 | 1060 |
| 85°C @ $V_{IN} = 5V$ | 825 | 955 |
| 125°C @ $V_{IN} = 5V$ | 510 | 590 |



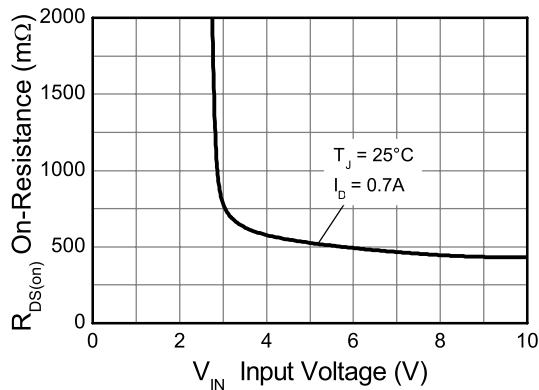
Typical characteristics



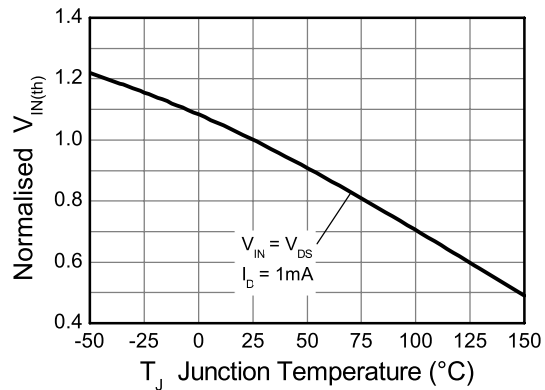
Typical Output Characteristic



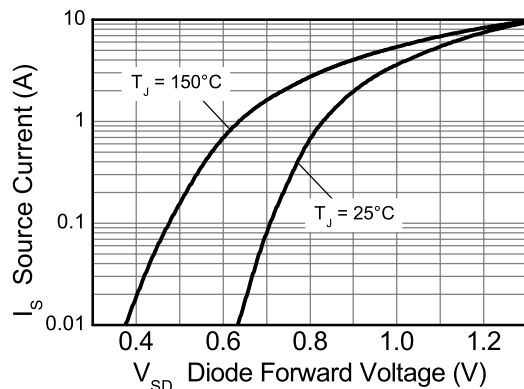
On-state Resistance vs Temperature



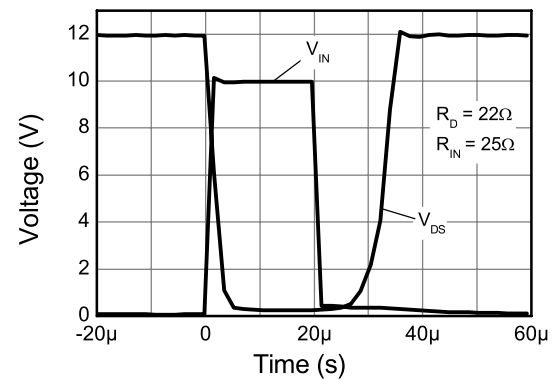
On-Resistance vs Input Voltage



Threshold Voltage vs Temperature

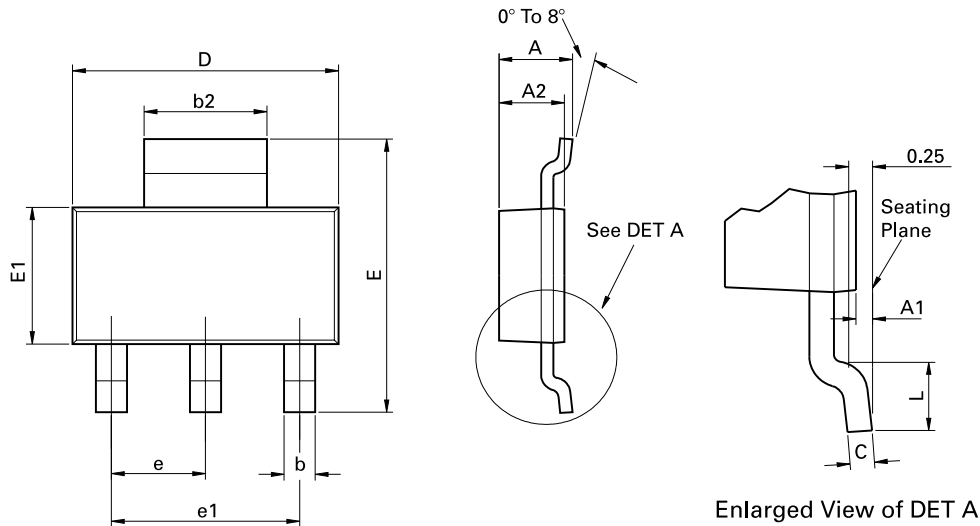


Source-Drain Diode Forward Voltage



Switching Speed

Package outline - SOT223



Conforms to JEDEC TO-261 AA Issue B

| Dim. | Millimeters | | Inches | | Dim. | Millimeters | | Inches | |
|------|-------------|------|--------|-------|------|-------------|------|------------|-------|
| | Min. | Max. | Min. | Max. | | Min. | Max. | Min. | Max. |
| A | - | 1.80 | - | 0.071 | e | 2.30 BSC | | 0.0905 BSC | |
| A1 | 0.02 | 0.10 | 0.0008 | 0.004 | e1 | 4.60 BSC | | 0.181 BSC | |
| b | 0.66 | 0.84 | 0.026 | 0.033 | E | 6.70 | 7.30 | 0.264 | 0.287 |
| b2 | 2.90 | 3.10 | 0.114 | 0.122 | E1 | 3.30 | 3.70 | 0.130 | 0.146 |
| C | 0.23 | 0.33 | 0.009 | 0.013 | L | 0.90 | - | 0.355 | - |
| D | 6.30 | 6.70 | 0.248 | 0.264 | - | - | - | - | - |

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

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